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Product Change Notification - JAON-13SZRI638 (Printer Friendly)

Date: 09 Oct 2016

Product Category: Memory; Analog (Linear & Mixed Signal) AND Interface; Analog

(Thermal, Power Management & Safety)

Notification CCB 1545 Final Notice: Qualification of CuPdAu bond wire,

subject: 8600 die attach and G700LTD mold compound material in

selected products of the 160K wafer technology available in 8L

TDFN package at NSEB site

Notification text: PCN Status:

Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN # Affected CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 160K wafer technology available in 8L TDFN package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site

Wire material	Au wire	CuPdAu wire
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire, 8600 die attach and G700LTD mold compound material at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

November 25, 2016 (date code: 1647)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2015			4	October 2016				November 2016				
Workweek	14	15	16	17		40	41	42	43	44	45	46	47
Initial PCN Issue Date			Х										
Qual Report Availability													
Final PCN Issue Date						X							
Estimated Implementation													

Date							Χ

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN # Qual Report.

Revision History:

April 24, 2015: Issued initial notification.

October 9, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from October 1, 2015 to November 25, 2016. Updated the affected parts list. Updated PCN letter to add the pre and post change summary table and the time table summary. Updated the subject and description to add the die attach and mold compound material.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN_JAON-13SZRI638_Qual Report.pdf

PCN_JAON-13SZRI638_Affected_ CPN.pdf PCN_JAON-13SZRI638_Affected_ CPN.xls

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